

BOARD CHARACTERISTICS

Copper Layer Count:2Board Thickness:1.6000 mm

Board overall dimensions:40.8940 mm x 101.4730 mm

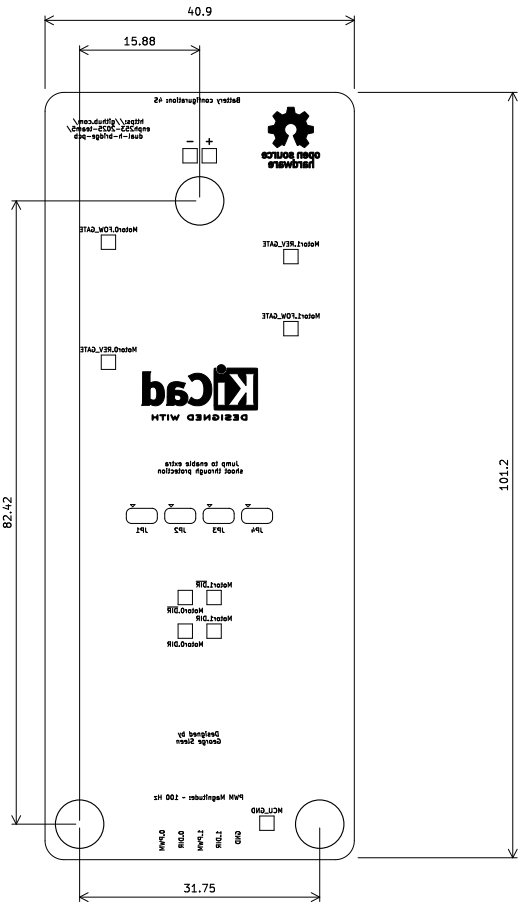
Min track/spacing:0.1000 mm / 0.1000 mmMin hole diameter:0.2500 mm

Copper Finish:NoneImpedance Control:No

Castellated pads:NoPlated Board Edge:No

Edge card connectors:No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



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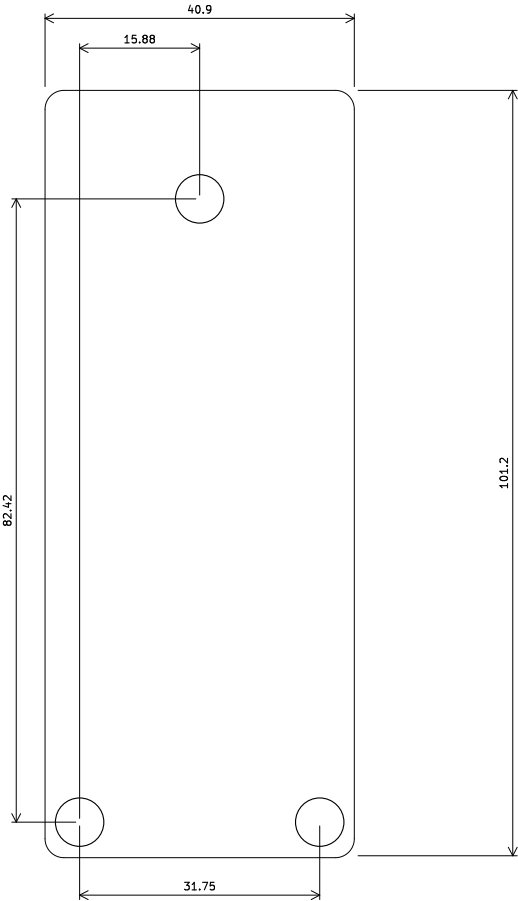
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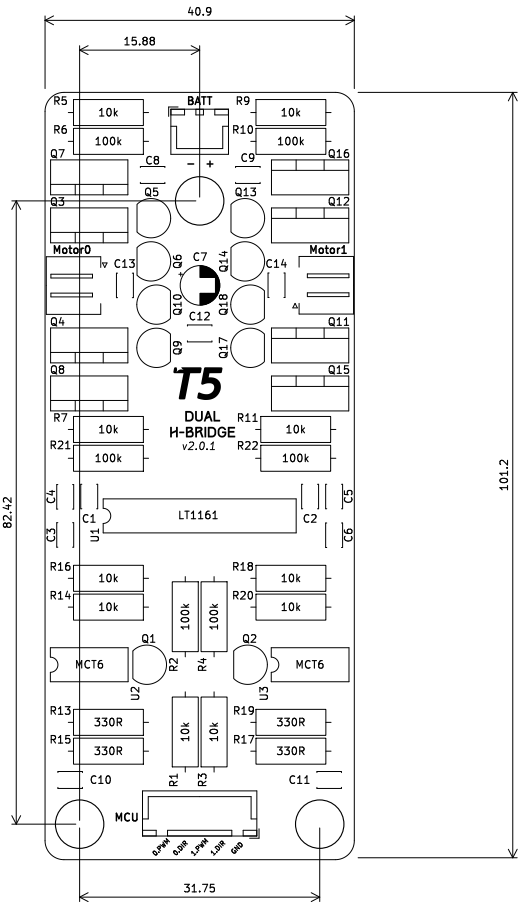
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